







Release Date: 27 June 2023 Version: A1.0







- ► Ceramic High Power
- ➤ 3535 1.95t Series
- ► Red 620-630nm

N0R62S64



3535 1.95t Series





FEATURES:

Package: Ceramic SMT Package with Silicon Lens

Forward Current: 350~500mA Forward Voltage (typ.): 2.1V

Luminous Flux (typ.): 50lm@350mA

Colour: Red

Wavelength: 620~630nm Viewing Angle: 120°

Materials:

Resin: Silicon (Water Clear)

L/T Finish: Ag-plated

Operating Temperature: -40~+85°C Storage Temperature: -40~+100°C

Grouping Parameters:

Forward Voltage

Luminous Flux

Dominant Wavelength

Soldering Methods: Reflow Soldering

MSL Level: Level 3 according to J-STD020

Packing: 12mm tape with max.1000pcs/reel, ø180mm (7'')

3535 1.95t Series

APPLICATIONS:

- Portable Lighting
- **Outdoor Lighting**
- Commercial Lighting
- **Indoor Lighting**
- **Industrial Lighting**
- Plant Grow Light



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
DC Forward Current	IF	500	mA
Reverse Voltage	V _R	5	V
Reverse Current @5V	I _R	10	μΑ
Junction Temperature	Tj	115	°C
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T _{STG}	-40~+100	°C
Soldering Temperature	T _{SOL}	260	°C
Thermal Resistance - Junction to Solder Point	R _{th}	12	°C/W

Electrical & Optical Characteristics (Ta=25°C)

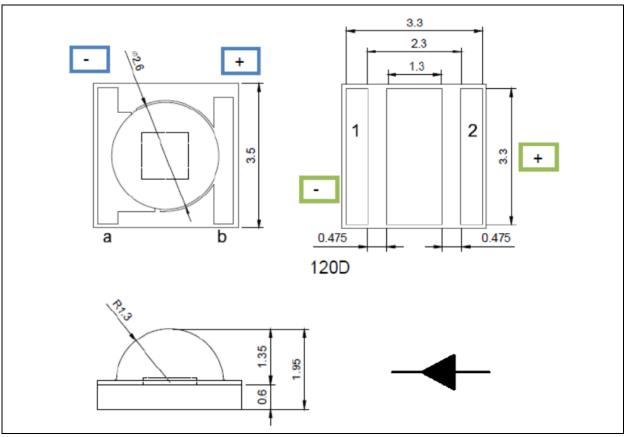
Darameter	Symbol	Values			l leit	Test
Parameter	Зуппоп	Min.	Тур.	Max.	Unit	Condition
Forward Voltage	VF	1.4		2.8	V	I _F =350mA
Luminous Flux	le	40		60	lm	I _F =350mA
Dominant Wavelength	λ _D	620		630	nm	I _F =350mA
Viewing Angle	2θ _{1/2}		120		deg	I _F =350mA

^{1.} Radiant Flux (Φ_V) ±5%, Forward Voltage (V_F) ±0.06V, Viewing angle($2\theta_{1/2}$) ±10°



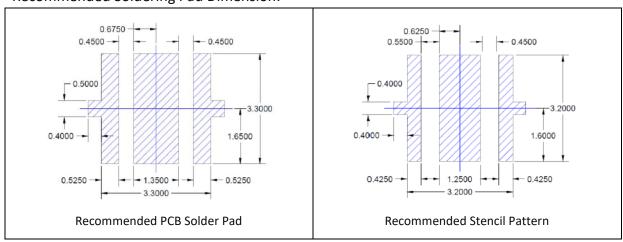
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.13mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.12mm with angle tolerance ±0.5°.



BINNING GROUPS:

Forward Voltage Classifications (I_F = 350mA):

Code	Min.	Max.	Unit
V14	1.4	1.6	
V16	1.6	1.8	
V18	1.8	2.0	
V20	2.0	2.2	V
V22	2.2	2.4	
V24	2.4	2.6	
V26	2.6	2.8	

Luminous Flux Classifications (I_F = 350mA):

Code	Min.	Max.	Unit
R24	40	45	
R25	45	50	lm
R26	50	55	lm
R27	55	60	

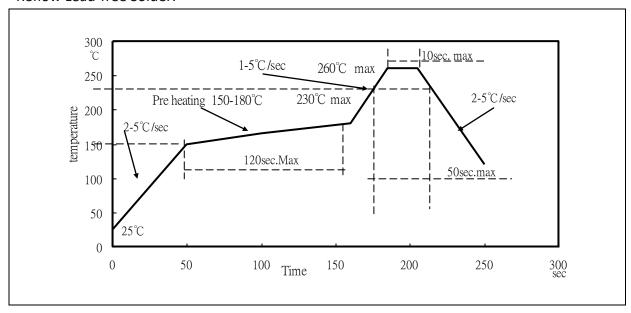
Dominant Wavelength Classifications (IF = 350mA):

Code	Min.	Max.	Unit
R1	620	625	
R2	625	630	nm



RECOMMENDED SOLDERING PROFILE:

Reflow Lead-free Solder:



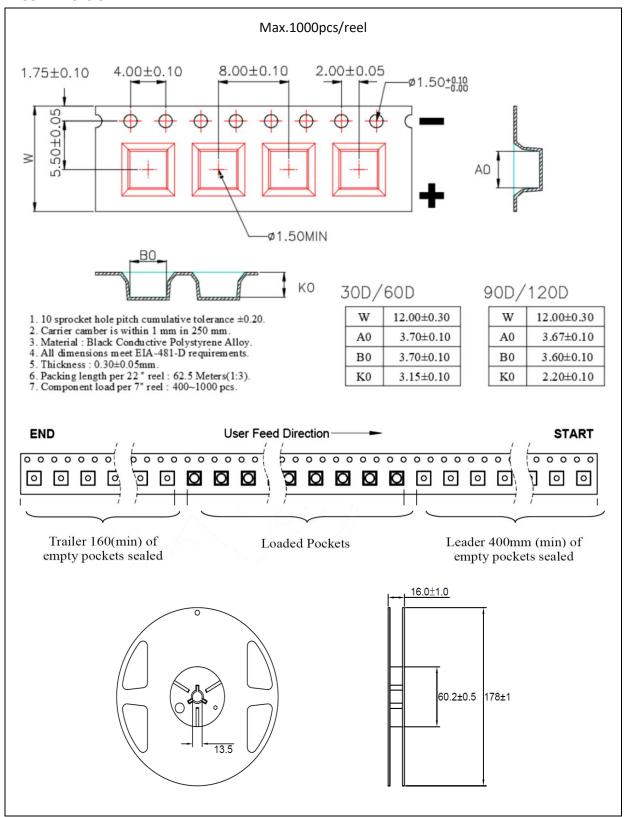
Note:

- 1. Maxima reflow soldering: 2 times.
- 2. The recommend reflow temperature is 240°C. The maxima soldering temperature should be limited to 260°C.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

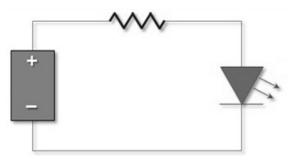
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±3°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	27/06/2023	Datasheet set-up.